



# Safety Certificated Capacitors X1/Y2

#### **■** HOW TO ORDER

<b>S2</b>	42	N	100	J	302	L	Т
<u>Series</u>	<u>Size</u>	<u>Dielectric</u>	<u>Capacitance</u>	<u>Tolerance</u>	Rated voltage	<u>Termination</u>	<u>Packaging</u>
S2=X1/Y2	42=1808 (4520) 43=1812 (4532)	N=NPO (COG)	Two significant digits followed by no. of zeros. And R is in place of decimal point.  eg.: 100=10x10° =10pF	J=±5% K=±10%	Two significant digits followed by no. of zeros. And R is in place of decimal point.  302=3000 VDC	L=Ag/Ni/Sn	B=Bulk T=7" reeled

#### ■ PACKAGING DIMENSION AND QUANTITY

Size	Thickness (mm)/Symbol		7" reel / Plastic tape
1808 (4520)	1.25±0.10	D	2k
	2.00±0.20	K	1k
1812 (4532)	1.25±0.10	D	1k
1012 (4332)	2.00±0.20	K	1k

Unit: pieces

### **■ CAPACITANCE RANGE**

	Dielectric		IPO	
	ted voltage (VAC)	250		
Rat	ted Voltage (VDC)	3000		
	Size	1808	1812	
	10pF (100)	D		
	12pF (120)	D	D	
	15pF (150)	D	D	
	18pF (180)	D	D	
	22pF (220)	D	D	
	27pF (270)	D	D	
	33pF (330)	D	D	
	39pF (390)	D	D	
d)	47pF (470)	D	D	
Ě	56pF (560)	D	D	
Capacitance	68pF (680)	D	D	
apć Apć	82pF (820)	D	D	
	100pF (101)	D	D	
	120pF (121)	D	D	
	150pF (151)	D	D	
	180pF (181)	K	D	
	220pF (221)	K	D	
	270pF (271)	K	K	
	330pF (331)		K	
	390pF (391)		K	
	470pF (471)		K	

<sup>1.</sup> The letter in cell is expressed the symbol of product thickness.

<sup>2.</sup> For more information about products with special capacitance or other data, please contact WTC local representative.



# Appendix I: Reliability Test Conditions and Requirements

NO.	Item	Test Condition	Requirements			
1.	Visual and Mechanical		No remarkable defect.     Dimensions to confirm to individual specification sheet.			
2.	Capacitance	Class I : NPO	* Shall not exceed the limits given in the detailed spec.			
3.	Q/ D.F. (Dissipation Factor)	Cap 1000pF 1.0±0.2Vrms, 1MHz±10% Cap>1000pF 1.0±0.2Vrms, 1KHz±10%	NPO: Cap 30pF, Q 1000; Cap<30pF, Q 400+20C X7R, X5R:			
	(Dissipation Factor)	OLAND VED VED	Rated vol. D.F. Exception of D.F.			
		Class II : X7R, X5R, Y5V Cap 10µF, 1.0±0.2Vrms, 1KHz±10%	50V 2.5% 3.0% All 0201;0603 0.047μF;0805 0.18μF;			
		Cap>10μF, 0.5±0.2Vrms, 120Hz±20%	25V 3.5% 5.0% 0805 1µF, 1210 10µF			
			7.0%   0603   0.33µF;TT series & Cap   1µF			
			16V 3.5% 0805 0.68μF;1206 2.2μF			
			10% TT series & Cap 1μF 10V 5.0% 10.0% TT series & Cap 1μF:0805 10μF			
			6.3V 10.0% 15.0% 0805 22μF;1210 100μF			
			Y5V:			
			Rated vol. D.F. Exception of D.F. 50V 5.0%			
			35V 7.0%			
			7.0% 0603 0.1µF; 0805 0.33µF;			
			25V 5.0% 7.0% 1206 1μF; 1210 4.7μF 9.0% 0402 0.068μF			
			16V (C<1.0μF) 7.0% 9.0% 0402 0.068μF; 0603 0.68μF			
			16V (C 1.0μF) 9.0% 12.5% 0805 4.7μF;1206 10μF;1210 22μF			
			10V 12.5% 6.3V 20.0%			
			0.37 20.070			
4a.	Dielectric Strength	* To apply voltage ( 50V) 250%.	* No evidence of damage or flash over during test.			
		* Duration: 1 to 5 sec.  * Charge & discharge current less than 50mA.				
	•	* To apply voltage :				
		100V 3 times V DC				
		200V ~ 300V 2 times V DC 500V ~ 999V 1.5 times V DC				
		1000V ~ 3000V 1.2 times V DC				
		* Cut-off, set at 10mA				
		* TEST= 15 sec. * RAMP=0				
4b.	Dielectric Strength (for X1/Y2 & X2/Y3)	* To apply 1500 VAC voltage.  * Duration: 60 sec.	* No evidence of damage or flash over during test.			
5.	Insulation Resistance	To apply rated voltage for max. 120 sec.	10G or RxC 500 -F whichever is smaller.			
		Rated voltage: 100 ~ 500V  To apply rated voltage for 60 sec.	10G			
		Rated voltage: To apply 500V for 60 sec.	10G			
		> 500V				
6.	Temperature	With no electrical load.				
	Coefficient	T.C. Operating Temp	T.C. Capacitance Change			
		NP0 (C0G) -55~125°C at 25°C NP0 (C0J) -55~125°C at 25°C	NP0 (COG)         Within ±30ppm/°C           NP0 (COJ)         Within ±120ppm/°C			
		X7R -55~125°C at 25°C	X7R Within ±15%			
		X5R -55~85°C at 25°C	X5R Within ±15%			
		Y5V -25~85°C at 20°C	Y5V Within +30%/-80%			
7.	Adhesive Strength	* Pressurizing force:	* No remarkable damage or removal of the terminations.			
	of Termination	0201: 2N				
		0402 & 0603: 5N >0603: 10N				
		* Test time: 10±1 sec.				
8.	Vibration	* Vibration frequency: 10~55 Hz/min.	* No remarkable damage.			
	Resistance	* Total amplitude: 1.5mm	* Cap change and Q/D.F.: To meet initial spec.			
		* Test time: 6 hrs. (Two hrs each in three				
		mutually perpendicular directions.)				



## Appendix I: Reliability Test Conditions and Requirements

NO.	Item	Test Condition	Requirements		
9.	Solderability	* Solder temperature: 235±5°C * Dipping time: 2±0.5 sec.	95% min. coverage of all metalized area.		
10.	Bending Test	* The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm per second until the deflection becomes 1 mm and then the pressure shall be maintained for 5±1 sec.  * Measurement to be made after keeping at room temp. for 24±2 hrs.	* No remarkable damage.  * Cap change: NP0: within ±5.0% or ±0.5pF whichever is larger. X7R, X5R: within ±12.5% Y5V: within ±30% (This capacitance change means the change of capacitance under specified flexure of substrate from the capacitance measured before the test.)		
11.	Resistance to Soldering Heat	* Solder temperature: 270±5°C  * Dipping time: 10±1 sec  * Preheating: 120 to 150°C for 1 minute before immerse the capacitor in an eutectic solder.  * Before initial measurement (Class II only): Perform 150+0/-10°C for 1 hr and then set for 48±4 hrs at room temp.  * Measurement to be made after keeping at room temp. for 24±2 hrs. (Class I) or 48±4 hrs. (Class II).	* No remarkable damage.  * Cap change:  NP0: within ±2.5% or ±0.25pF whichever is larger.  X7R, X5R: within ±7.5%  Y5V: within ±20%  * Q/D.F., I.R. and dielectric strength: To meet initial requirements.  * 25% max. leaching on each edge.		
12.	Temperature Cycle	* Conduct the five cycles according to the temperatures and time.    Step   Temp. (°C)   Time (min.)     1   Min. operating temp. +0/-3   30±3     2   Room temp.   2~3     3   Max. operating temp. +3/-0   30±3     4   Room temp.   2~3     * Before initial measurement (Class II only): Perform 150+0/-10°C for 1 hr and then set for 48±4 hrs at room temp.     * Measurement to be made after keeping at room temp. for 24±2 hrs. (Class I) or 48±4 hrs. (Class II).	* No remarkable damage.  * Cap change: NPO: within ±2.5% or ±0.25pF whichever is larger. X7R, X5R: within ±7.5% Y5V: within ±20%  * Q/D.F., I.R. and dielectric strength: To meet initial requirements.		
13.	Humidity (Steady State)	* Test temp.: 40±2°C  * Humidity: 90~95% RH  * Test time: 500+24/-0hrs.  * Measurement to be made after keeping at room temp. for 24±2 hrs. (Class I) or 48±4 hrs. (Class II).	* No remarkable damage.  * Cap change: NPO: within ±5.0% or ±0.5pF whichever is larger.  X7R, X5R: 10V, within ±12.5% 6.3V, within ±25% Y5V: within ±30%  * Q/D.F. value:  NPO: Cap 30pF, Q 350; 10pF Cap<30pF, Q 275+2.5C Cap<10pF; Q 200+10C  X7R, X5R:  Rated vol. D.F.   Exception of D.F.  50V		



# Appendix I: Reliability Test Conditions and Requirements

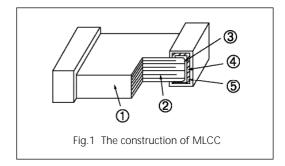
NO.	Item	Test Condition	Requirements		
14.	Humidity Load (Damp Heat)	* Test temp.: 40±2°C  * Humidity: 90~95%RH  * Test time: 500+24/-0 hrs.  * To apply voltage: rated voltage (Max. 500V)  * Measurement to be made after keeping at room temp. for 24±2 hrs. (Class I) or 48±4 hrs. (Class II).	* No remarkable damage.  * Cap change: NPO: within ±7.5% or ±0.75pF whichever is larger.  X7R, X5R: 10V, within ±12.5%  6.3V, with ±25%  Y5V: 10V, within ±30%  6.3V, within ±30 to -40%  * Q/D.F. value:  NPO: Cap 30pF, Q 200; Cap<30pF, Q 100+10/3C		
			X7R, X5R:   Rated vol.   D.F.   Exception of D.F.		
			Rated vol.   D.F.   Exception of D.F.   50V   7.5%		
15.	High Temperature Load (Endurance)	* Test temp.:  NPO, X7R: 125±3°C  X5R, Y5V: 85±3°C  * To apply voltage:  (1) 6.3V or C 10µF (for X7R, X5R): 150% of rated voltage.  (2) 6.3V<√<500V and C<10µF (for X7R, X5R):  200% of rated voltage.  (3) 500V: 150% of rated voltage.  (4) V 630V: 120% of rated voltage. (Max. 3600V)  * Test time: 1000+24/-0 hrs.  * Measurement to be made after keeping at room temp. for 24±2 hrs. (Class I) or 48±4 hrs. (Class II).  * No remarkable damage.  * Cap change: NPO: within ±3.0% or ±0.3pF which:  X7R, X5R: 10V, within ±30%  6.3V, within ±30%  6.3V, within ±30 to -40%  * O/D.F. value:  NPO: Cap 30pF, Q 350  10pF Cap<30pF, Q 275±2.5C  Cap<10pF, Q 200+10C  X7R, X5R:    Rated vol.   D.F.   Exception of D.F.			
			TT series & Cap 1μF		



### **Appendix II: General Information**

#### Constructions

No.	Na	me	NPO/X7R	X7R/X5R/Y5V
1	Ceramic	material	BaTiO <sub>3</sub>	based
2	Inner el	ectrode	AgPd alloy	Ni
3		Inner layer	Ag	Cu
4	Termination	Middle layer	Ni	
5		Outer layer	Sn (Matt)	



### Storage and handling conditions

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

#### Cautions:

- a. Don't store products in a corrosive environment such as sulfide, chloride gas, or acid. It may cause oxidization of electrode, which easily be resulted in poor soldering.
- b. To store products on the shelf and avoid exposure to moisture.
- c. Don't expose products to excessive shock, vibration, direct sunlight and so on.

### Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N<sub>2</sub> within oven are recommended.

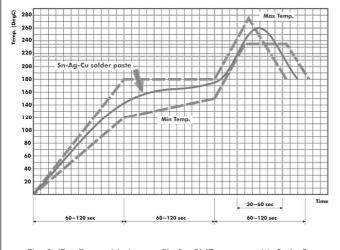


Fig. 2 IR reflow soldering profile for SMT process with SnAgCu series solder paste.

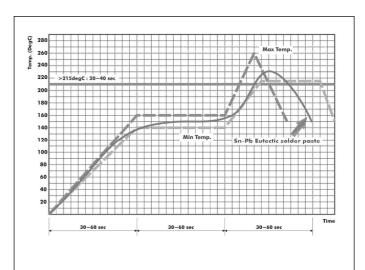


Fig. 3 IR reflow soldering profile for SMT process with eutectic SnPb solder paste.